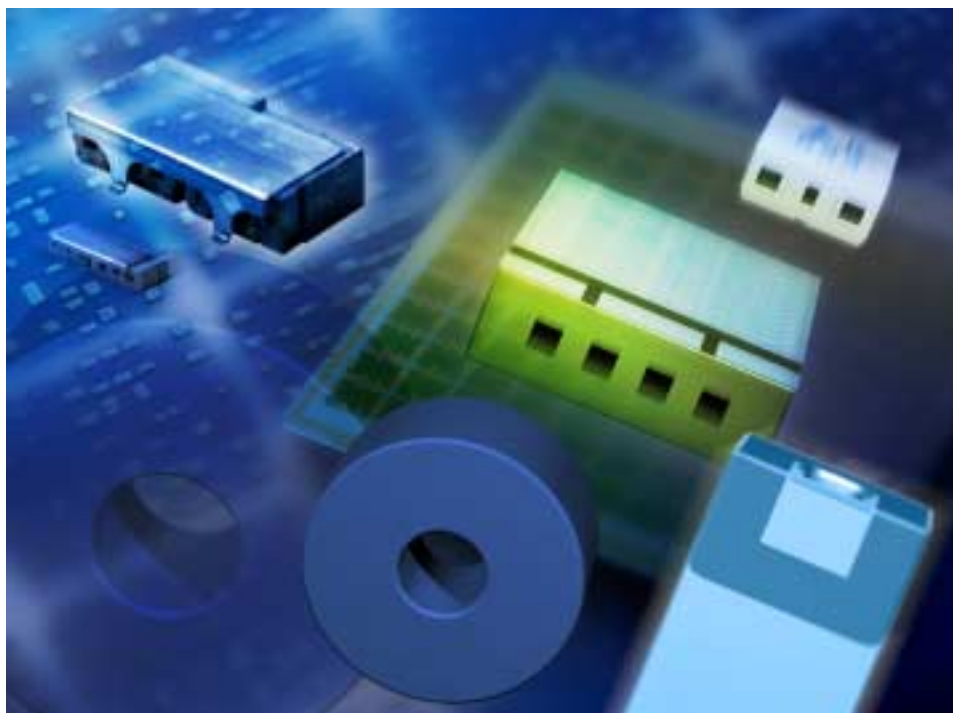


Preliminary data



## Features

- SMD filter consisting of coupled resonators with stepped impedances
- $\text{MgTiO}_3\text{-CaTiO}_3$  ( $\epsilon_r = 21$  /  $TC_f = 0 \pm 10$  ppm/K) with a coating of copper ( $10\mu\text{m}$ ) and tin ( $>5\mu\text{m}$ )
- Excellent reflow solderability, no migration effect due to copper/tin metallization

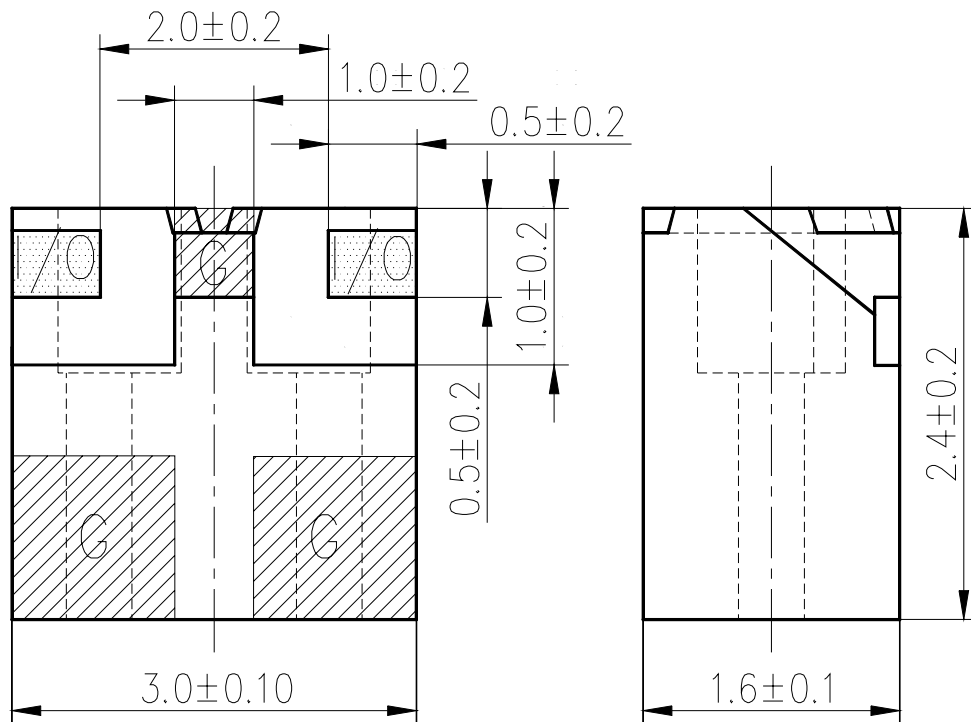
## Index

- Page 2
  - Component drawing
  - Recommended footprint
- Page 3
  - Characteristics
  - Maximum ratings
  - Typical passband characteristic
- Page 4
  - Processing information
  - Soldering requirements
  - Delivery mode

ISSUE DATE	16.09.03	ISSUE	P2	PUBLISHER	MWK M PE	PAGE	1/4
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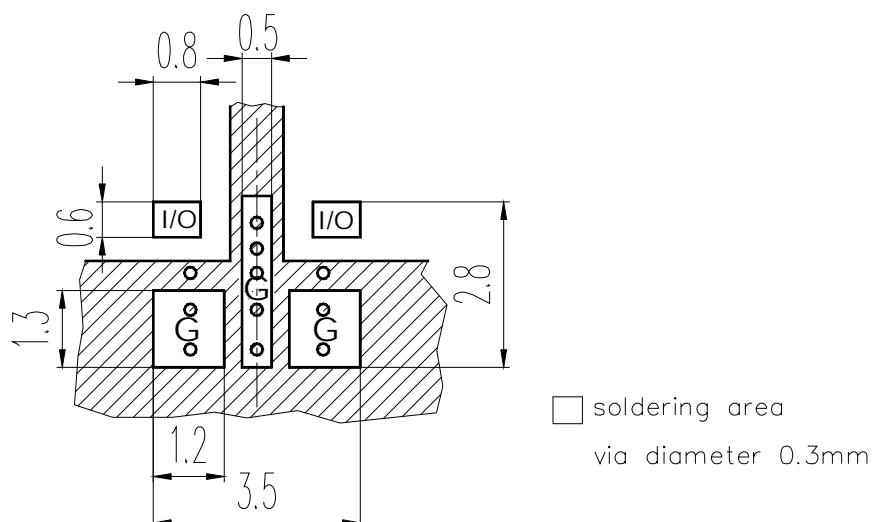
Preliminary data

Component drawing



S2H11\_010601.DWG→WMF

Recommended footprint



FOOTPR\_240502.DWG→WMF

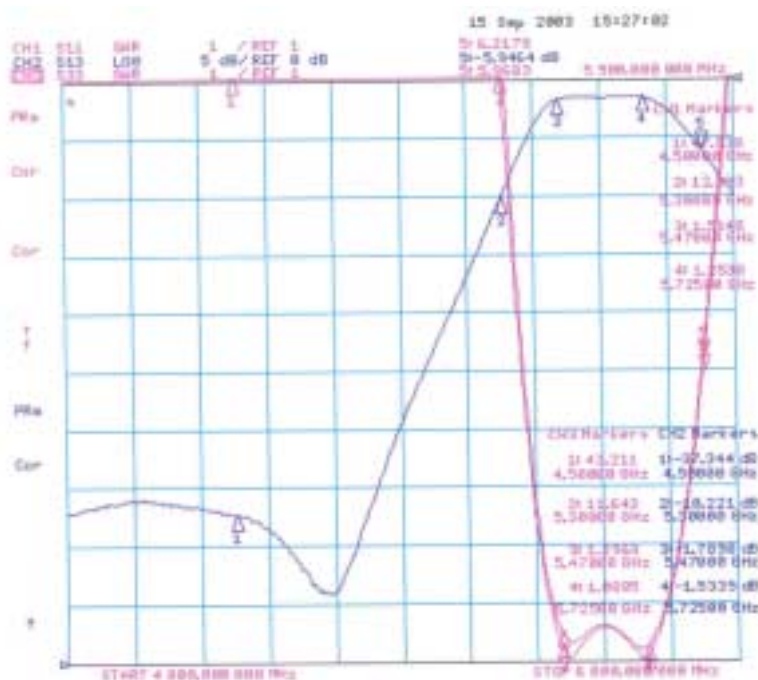
ISSUE DATE	16.09.03	ISSUE	P2	PUBLISHER	MWK M PE	PAGE	2/4
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**Preliminary data**
**Characteristics**

		min.	typ.	max.	
Center frequency	$f_c$	-	5597.5	-	MHz
Insertion loss	$\alpha_{IL}$		1.3	1.6	dB
Passband	$B$	255			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$				dB
Standing wave ratio	SWR		1.5	2.0	
Impedance	$Z$		50		$\Omega$
Power	$P$			1.0	W
Attenuation	$\alpha$				
	at DC to 4500 MHz	35	40		dB
	at 5300 MHz	8			dB
	at 5900 MHz	5			dB

**Maximum ratings**

IEC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	$T_{op}$	-40 / + 85	°C

**Typical passband characteristic**


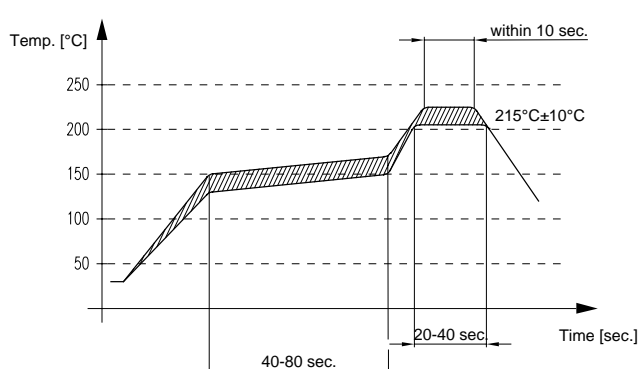
**Preliminary data**
**Processing information**

ZNr.: 577 (FILT95\_2)

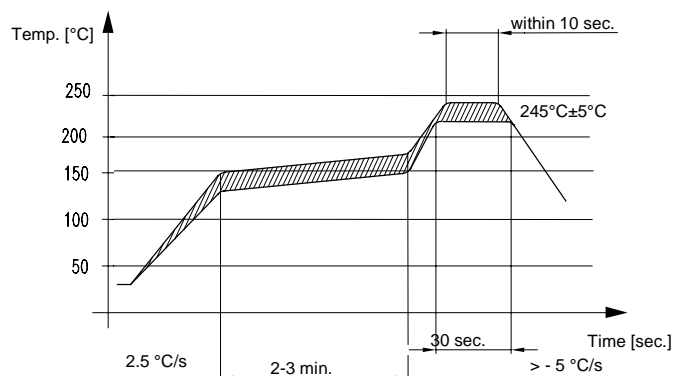
- Wettability to IEC 68-2-58:  $\geq 75\%$  (after aging)

**Soldering requirements**

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

**Recommended soldering conditions (infrared):**


eutectic SnPb solder paste profile



leadfree solder paste profile

**Delivery mode**

- Blister tape acc. to IEC 286-3, PS, grey
- Pieces/tape: 4000

t.b.d.

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ISSUE DATE	16.09.03	ISSUE	P2	PUBLISHER	MWK M PE	PAGE	4/4
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